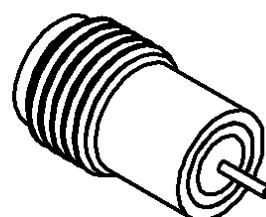
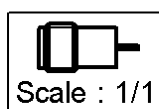
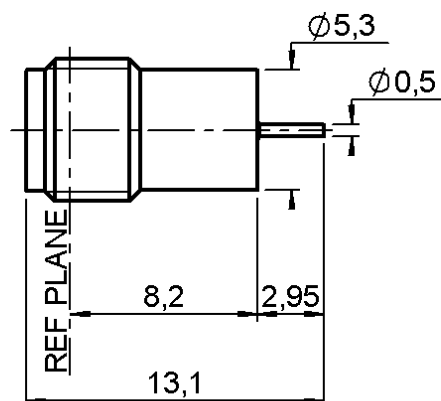


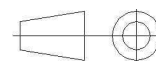
SOLDER JACK RECEPTACLE
HERMETIC-WITH CYLINDRICAL CONTACT

R125.630.040

Series : SMA



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY	INOX	GOLD 0.5 OVER NICKEL 2
CENTER CONTACT	DILVER P	GOLD 0.5 OVER NICKEL 2
OUTER CONTACT	-	-
INSULATOR	PTFE	-
GASKET	-	-
OTHERS PARTS	-	-
-	-	-
-	-	-

Issue : 1220 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



SOLDER JACK RECEPTACLE**HERMETIC-WITH CYLINDRICAL CONTACT****R125.630.040**

Series : SMA

PACKAGING

Standard	Unit	Other
1	-	Contact us

SPECIFICATION**ELECTRICAL CHARACTERISTICS**

Impedance	50	Ω
Frequency	0-18	GHz
VSWR	1.10 + 0,0100	x F(GHz) Maxi
Insertion loss	0.3	$\sqrt{F}$ (GHz) dB Maxi
RF leakage	- (NA)	- F(GHz)) dB Maxi
Voltage rating	500	Veff Maxi
Dielectric withstanding voltage	1000	Veff mini
Insulation resistance	5000	M Ω mini

ENVIRONMENTAL

Operating temperature	-40/+100	$^{\circ}$ C
Hermetic seal	10-5	Atm.cm3/s
Panel leakage	NA	

OTHERS CHARACTERISTICS

Assembly instruction

Others :
Coaxial Transmission Line Only

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	27	N mini
Axial force – Opposite end	27	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	500	Cycles mini
Weight	1,1500	g

Issue : 1220 A

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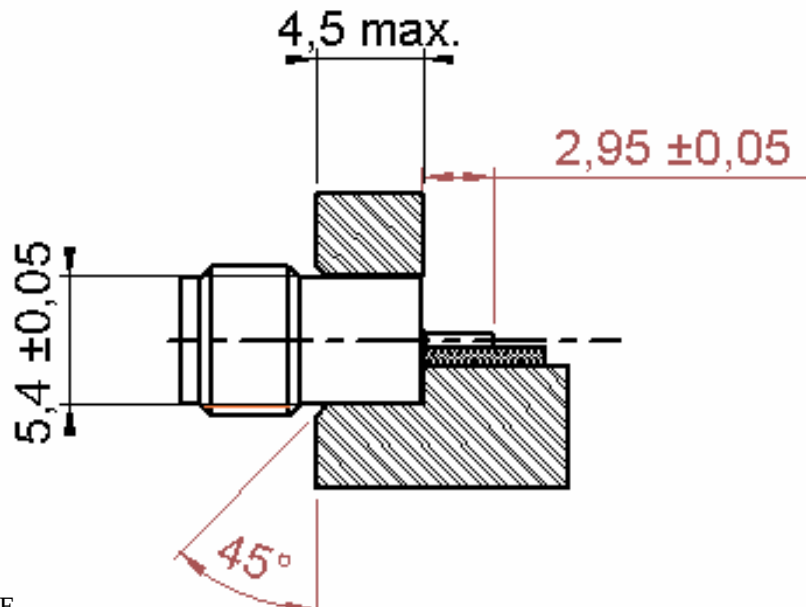
SOLDER JACK RECEPTACLE
HERMETIC-WITH CYLINDRICAL CONTACT

R125.630.040

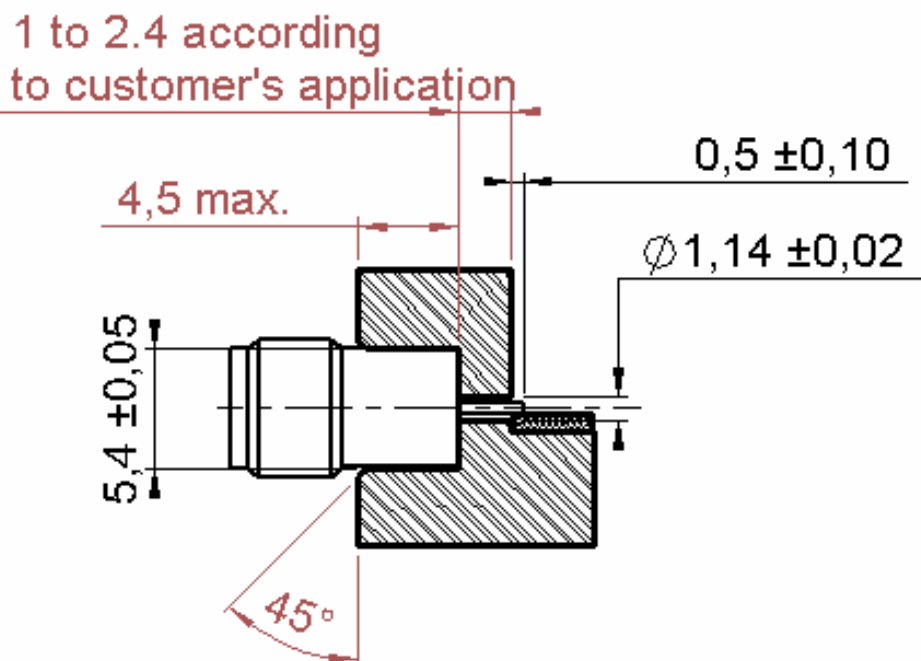
Series : SMA

RECOMMENDED MOUNTING HOLE DETAIL**PANEL WITH THROUGH HOLE**

Frequency range 0 – 18 GHz
VSWR < 1.10 + 0.03 F

**PANEL WITH BLIND HOLE**

Frequency range 0 – 18 GHz
VSWR < 1.05+0.02F

**Issue : 1220 A**

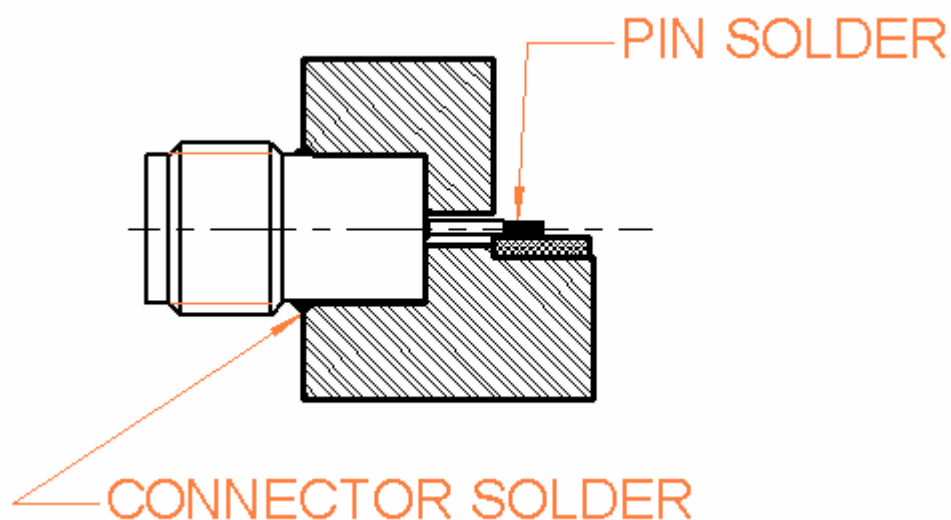
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SOLDER JACK RECEPTACLE
HERMETIC-WITH CYLINDRICAL CONTACT

R125.630.040

Series : SMA

MOUNTING INSTRUCTIONS

- 1 – Degrease and clean connector and box.
- 2 – Solder the connector on the panel:
Preheating at about 100°C.
Take care not to exceed 250°C during solder operation .
- 3 – Solder the pin on the track:
-ceramic substrates: preheating at about 100°C.
-other substrates: no preheating required.

NOTE: Please use a small soldering iron ,or hot air soldering system.

Issue : 1220 A

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